

SOT956-1

plastic thermal enhanced very thin small outline package; no leads; 16 terminals; body 1.35 x 3.3 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON16
Package type industry code	HVSON16
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-8-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.2	-	3.3	3.4	mm
E	package width		1.25	-	1.35	1.45	mm
A	seated height		[tbd]	-	0.85	1	mm
A ₂	package height		[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination		-	-	16	-	



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2. Package outline

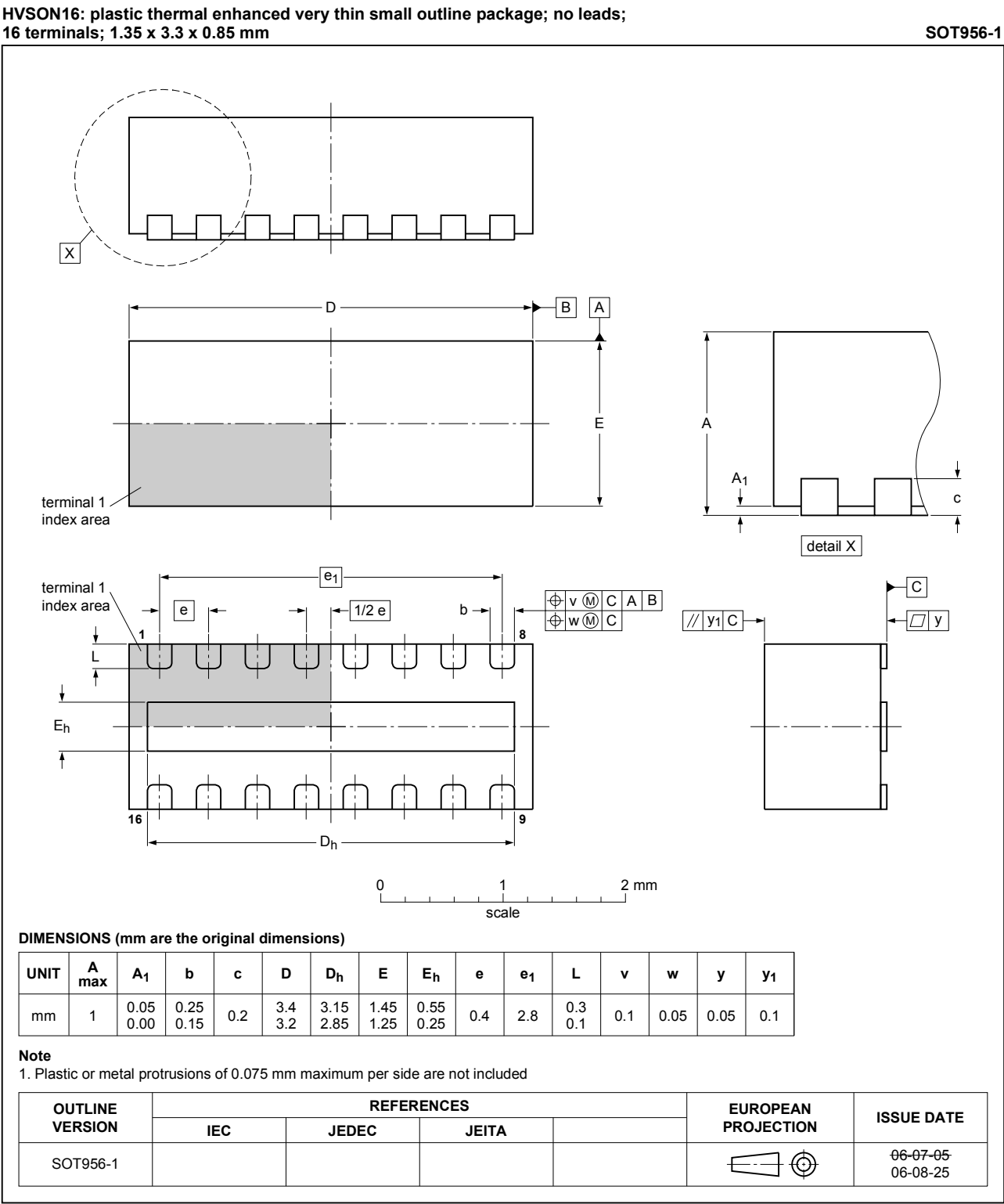


Fig. 1. Package outline HVSON16 (SOT956-1)

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3. Legal information

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Date of release: 8 February 2016